

P-Channel 100V(D-S) MOSFET

| Product summary | | |
|--|------|------------|
| V_{DS} | -100 | V |
| $R_{DS(ON)}$ (at $V_{GS}=-10V$) Typ. | 75 | m Ω |
| $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) Typ. | 85 | m Ω |
| I_D ($T_C=25^\circ C$) | -18 | A |

Features

- Spit Gate Trench MOSFET technology
- Extremely low switching loss
- Excellent stability and uniformity

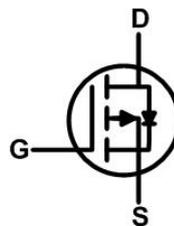
Applications

- Portable equipment
- Power management

Pin Configuration



TO-252



Packing Information

| Device | Package | Reel Size | Quantity(Min. Package) |
|------------|---------|-----------|------------------------|
| ECFA18P10A | TO-252 | 13" | 2500pcs |

Absolute Maximum Ratings (at $T_A=25^\circ C$ Unless Otherwise Noted)

| Symbol | Parameter | Rating | Units |
|----------------|---|------------------|------------|
| V_{DS} | Drain-Source Voltage | -100 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| I_D | Continuous Drain Current ^A | $T_C=25^\circ C$ | -18 |
| | | $T_C=70^\circ C$ | -12 |
| I_{DM} | Pulse Drain Current Tested ^B | -72 | A |
| E_{AS} | Avalanche energy ^C | 100 | mJ |
| P_D | Power Dissipation ^D | $T_C=25^\circ C$ | 72 |
| T_J, T_{STG} | Junction and Storage Temperature Range | -55 to +150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Typical | Units |
|-----------------|--|---------|--------------|
| $R_{\theta JA}$ | Thermal Resistance-Junction to ambient ^A | 45 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance-Junction to case max ^A | 1.7 | $^\circ C/W$ |

Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Units |
|--|---|---|------|------|-----------|------------|
| Static Parameters | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -100 | -- | -- | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=-100V, V_{GS}=0V$ | -- | -- | -1 | μA |
| | Zero Gate Voltage Drain Current $T_J=125^\circ\text{C}$ | $V_{DS}=-100V, V_{GS}=0V$ | -- | -- | -10 | μA |
| I_{GSS} | Gate-Body Leakage Current | $V_{DS}=0V, V_{GS}=\pm 20V$ | -- | -- | ± 100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -1.0 | -1.8 | -2.5 | V |
| $R_{DS(ON)}$ | Drain-Source On-State Resistance ^B | $V_{GS}=-10V, I_D=-10A$ | -- | 75 | 90 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-5A$ | -- | 85 | 110 | m Ω |
| V_{SD} | Forward Voltage ^B | $I_S=-10A, V_{GS}=0V$ | -- | -- | -1.3 | V |
| Dynamic Parameters ^E | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS}=0V, V_{DS}=-50V$ $f=1\text{MHz}$ | -- | 1051 | -- | pF |
| C_{oss} | Output Capacitance | | -- | 119 | -- | pF |
| C_{rss} | Reverse Transfer Capacitance | | -- | 25 | -- | pF |
| Q_g | Total Gate Charge | $V_{DS}=-50V, I_D=-5A$ $V_{GS}=-10V$ | -- | 20.1 | -- | nC |
| Q_{gs} | Gate-Source Charge | | -- | 3.9 | -- | nC |
| Q_{gd} | Gate-Drain Charge | | -- | 4.3 | -- | nC |
| $t_{D(on)}$ | Turn-on Delay Time | $V_{DD}=-50V$ $V_{GS}=-10V, R_G=6\Omega,$ $R_L=2.5\Omega$ | -- | 10 | -- | ns |
| t_r | Turn-on Rise Time | | -- | 30 | -- | ns |
| $t_{D(off)}$ | Turn-off Delay Time | | -- | 77 | -- | ns |
| t_f | Turn-off Fall Time | | -- | 81 | -- | ns |
| t_{rr} | Reverse recovery time | $I_F=-5A,$ $di/dt=100\text{ A/uS}$ | -- | 140 | -- | ns |
| Q_{rr} | Reverse recovery charge | | -- | 70 | -- | nC |

Note:

- A. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- B. The data tested by pulsed, Pulse Width $\leq 300\mu s$, Duty cycle $\leq 2\%$.
- C. The E_{AS} data shows Max. rating . The test condition is $V_{DD}=-50V, L=0.5mH, R_G=25\Omega$.
- D. The power dissipation is limited by 150°C junction temperature.
- E. Guaranteed by design, not subject to production testing.

Typical Characteristics

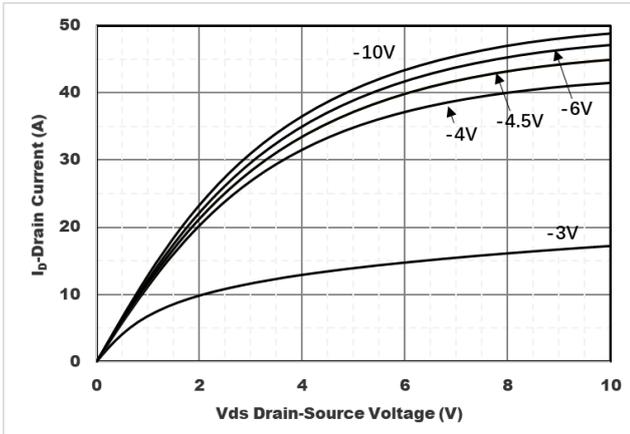


Figure1. Output Characteristics

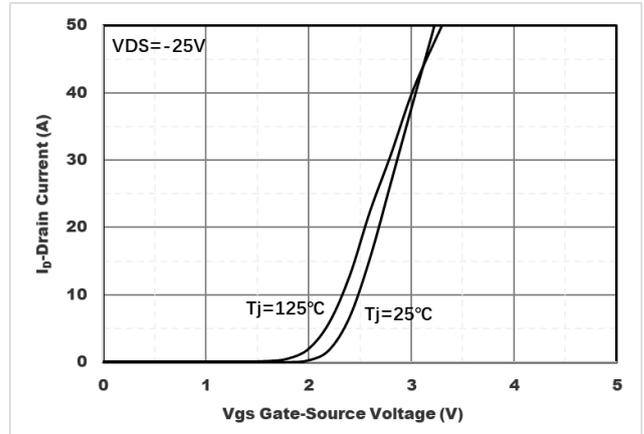


Figure2. Transfer Characteristics

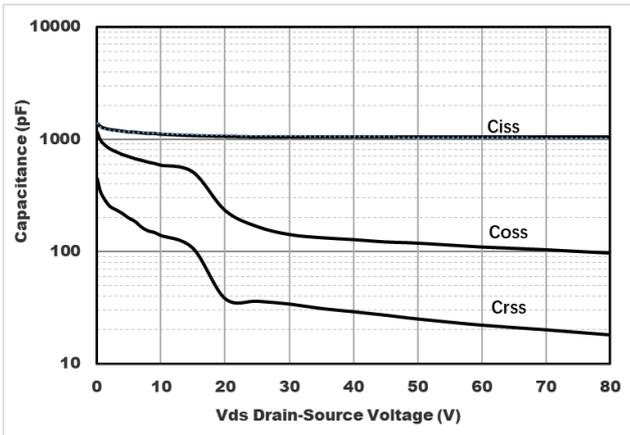


Figure3. Capacitance Characteristics

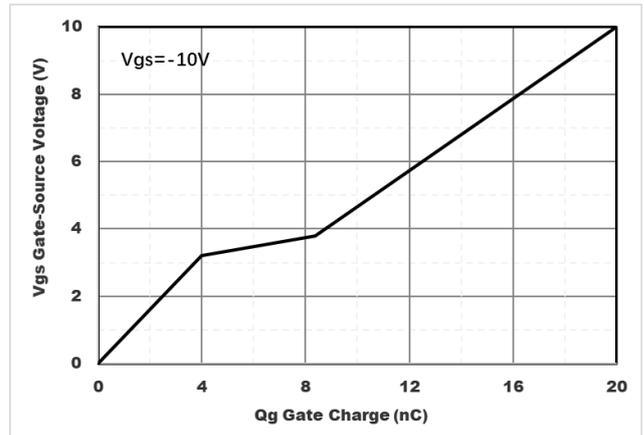


Figure4. Gate Charge

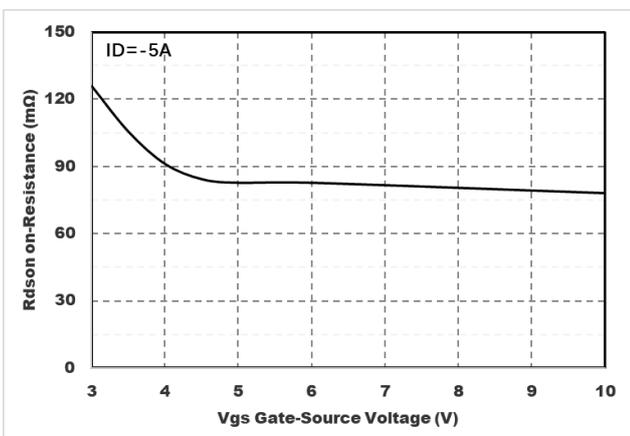


Figure5. : On-Resistance vs. Gate to Source Voltage

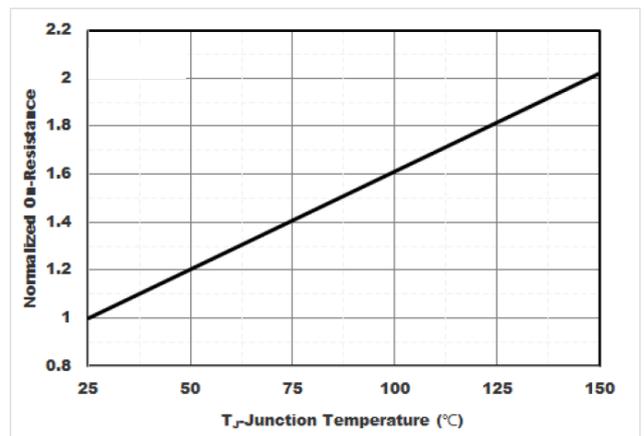


Figure6. Normalized On-Resistance

Typical Characteristics

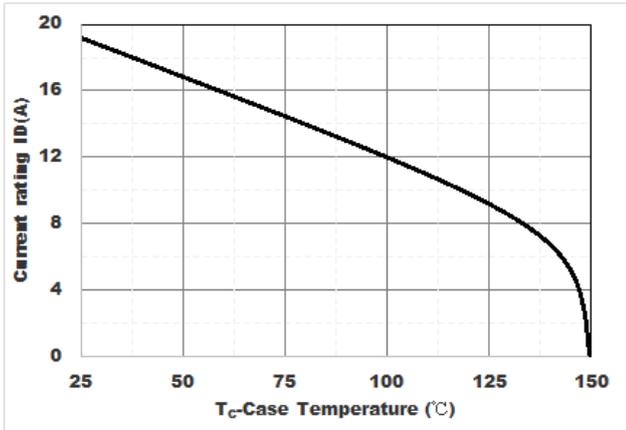


Figure7. Drain current

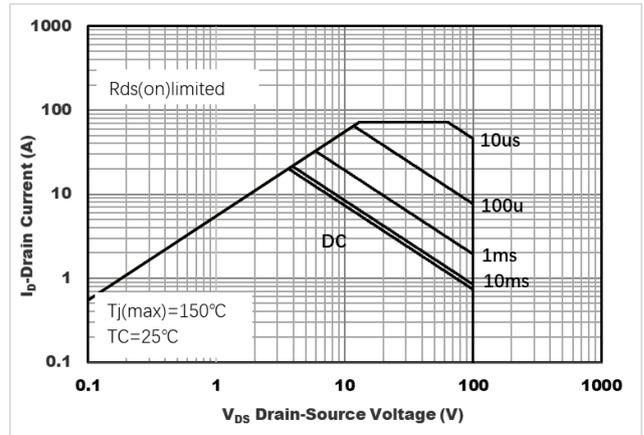


Figure8.Safe Operation Area

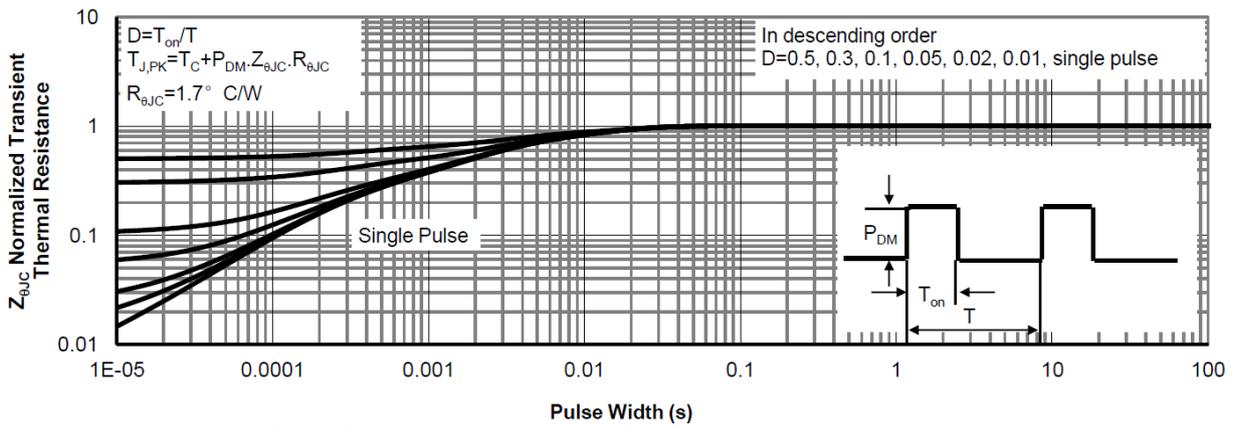
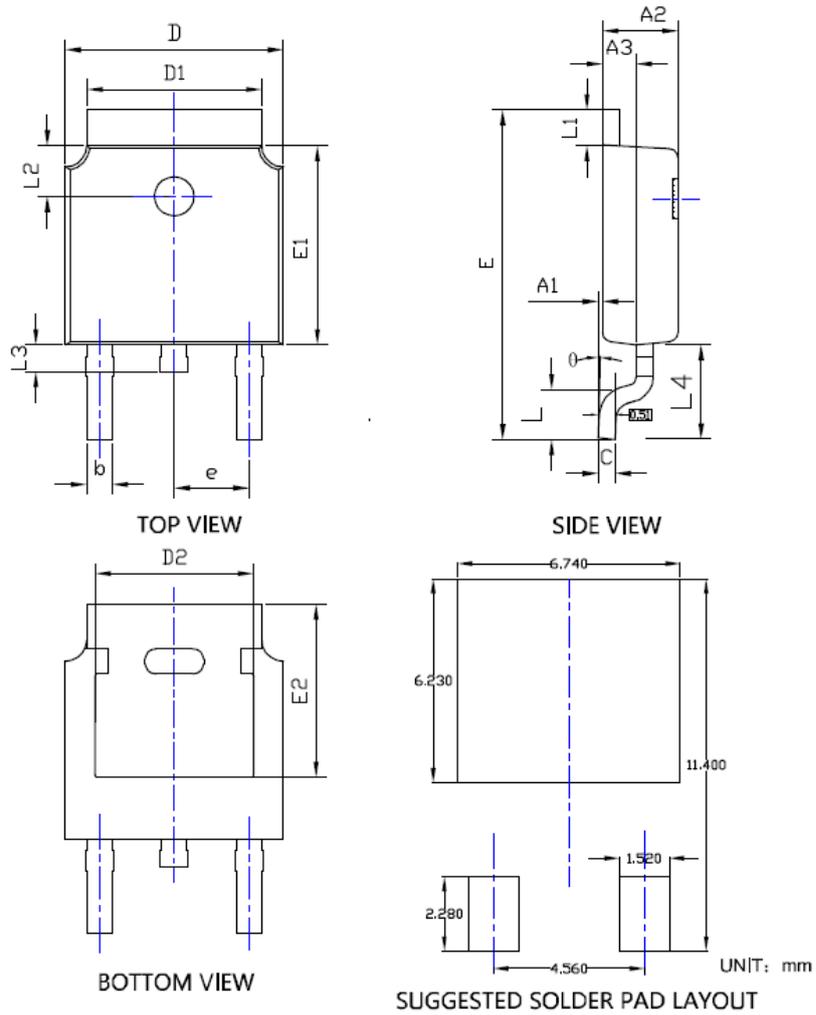


Figure9.Normalized Maximum Transient thermal impedance

TO-252 Package Information



| DIMENSIONS | | | | | | |
|------------|----------|-------|-------|------------|--------|--------|
| SYMBOL | INCHES | | | Millimeter | | |
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A1 | 0.000 | --- | 0.008 | 0.000 | --- | 0.200 |
| A2 | 0.087 | 0.091 | 0.094 | 2.200 | 2.300 | 2.400 |
| A3 | 0.035 | 0.039 | 0.043 | 0.900 | 1.000 | 1.100 |
| b | 0.026 | 0.030 | 0.034 | 0.660 | 0.760 | 0.860 |
| c | 0.018 | 0.020 | 0.023 | 0.460 | 0.520 | 0.580 |
| D | 0.256 | 0.260 | 0.264 | 6.500 | 6.600 | 6.700 |
| D1 | 0.203 | 0.209 | 0.215 | 5.150 | 5.300 | 5.450 |
| D2 | 0.181 | 0.189 | 0.195 | 4.600 | 4.800 | 4.950 |
| E | 0.390 | 0.398 | 0.406 | 9.900 | 10.100 | 10.300 |
| E1 | 0.236 | 0.240 | 0.244 | 6.000 | 6.100 | 6.200 |
| E2 | 0.203 | 0.209 | 0.215 | 5.150 | 5.300 | 5.450 |
| e | 0.090BSC | | | 2.286BSC | | |
| L | 0.049 | 0.059 | 0.069 | 1.250 | 1.500 | 1.750 |
| L1 | 0.035 | --- | 0.050 | 0.900 | --- | 1.270 |
| L2 | 0.055 | --- | 0.075 | 1.400 | --- | 1.900 |
| L3 | 0.240 | 0.310 | 0.039 | 0.600 | 0.800 | 1.000 |
| L4 | 0.114REF | | | 2.900REF | | |
| θ | 0° | --- | 10° | 0° | --- | 10° |